National Semiconductor

MICROCIRCUIT DATA SHEET

MN54F164A-X REV 1B0

Original Creation Date: 03/19/96
Last Update Date: 06/21/02
Last Major Revision Date: 03/19/96

SERIAL-IN, PARALLEL-OUT SHIFT REGISTER

General Description

The F164A is a high-speed 8-bit serial-in/parallel-out shift register. Serial data is entered through a 2-input AND gate synchronous with the LOW-to-HIGH transition of the clock. The device features an asynchronous Master Reset which clears the register, setting all outputs LOW independent of the clock.

Industry Part Number

54F164A

Prime Die

M164A

Controlling Document

SEE FEATURES SECTION

NS Part Numbers

54F164ADM-MLS
54F164ADMQB.
54F164AFMQB.
54F164ALMQB.

Processing

MIL-STD-883, Method 5004

Quality Conformance Inspection

MIL-STD-883, Method 5005

Subgrp	Description	Temp (°C)
1	Static tests at	+25
2	Static tests at	+125
3	Static tests at	-55
4	Dynamic tests at	+25
5	Dynamic tests at	+125
6	Dynamic tests at	-55
7	Functional tests at	+25
8A	Functional tests at	+125
8B	Functional tests at	-55
9	Switching tests at	+25
10	Switching tests at	+125
11	Switching tests at	-55

Features

- Asynchronous Master Reset
- Gated Serial Data Input
- Fully Synchronous Data Transfers

CONTROLLING DOCUMENT:

54F164ADMQB.	5962-8607101CA
54F164AFMQB.	5962-8607101DA
54F164ALMQB.	5962-86071012A

(Absolute Maximum Ratings)

(Note 1)

Storage Temperature	-65 C to +150 C
Ambient Temperature under Bias	-55 C to +125 C
Junction Temperature under Bias	-55 C to +175 C
Vcc Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0mA
Voltage Applied to Output in HIGH State (with Vcc=0V)	
Standard Output	-0.5V to Vcc
TRI-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated Iol(mA)
ESD Last Passing Voltage (Min)	4000V

Note 1: Absolute Maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.
Note 2: Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

Free Air Ambient Temperature	
Commercial	0 C to +70 C
Military	-55 C to +125 C
Supply Voltage	
Military	+4.5V to +5.5V
Commercial	+4.5V to +5.5V

Electrical Characteristics

DC PARAMETER

(The following conditions apply to all the following parameters, unless otherwise specified.)
DC: VCC 4.5V to 5.5V, TEMP RANGE: -55C to 125C

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
IIH	Input High Current	VCC=5.5V, VM=2.7V, VINH=5.5V, VINL=0.0V	1, 3	INPUTS		20	uA	1, 2, 3
IBVI	Input High Current	VCC=5.5V, VM=7.0V, VINH=5.5V, VINL=0.0V	1, 3	INPUTS		100	uA	1, 2, 3
IIL	Input LOW Current	VCC=5.5V, VM=0.5V, VINH=5.5V, VINL=0.0V	1, 3	INPUTS		-0.6	mA	1, 2, 3
VOL	Output LOW Voltage	VCC=4.5V, VIL=0.8V, IOL=20mA	1, 3	OUTPUTS		0.5	V	1, 2, 3
VOH	Output HIGH Voltage	VCC=4.5V, VIL=0.8V, IOH=-1.0mA, VIH=2.0V, VINH=5.5V	1, 3	OUTPUTS	2.5		V	1, 2, 3
IOS	Short Circuit Current	VCC=5.5V, VINH=5.5V, VM=0.0V	1, 3	OUTPUTS	-60	-150	mA	1, 2, 3
VCD	Input Clamp Diode Voltage	VCC=4.5V, IM=-18mA, VINH=5.5V	1, 3	INPUTS		-1.2	V	1, 2, 3
ICC	Supply Current	VCC=5.5V, VINL=0.0V, VINH=5.5V	1, 3	VCC		55	mA	1, 2, 3
ICEX	Output HIGH Leakage Current	VCC=5.5V, VINL=0.0V, VINH=5.5V	1, 3	OUTPUTS		250	uA	1, 2, 3

Electrical Characteristics

AC PARAMETER

(The following conditions apply to all the following parameters, unless otherwise specified.)
AC: CL=50pf, RL=500 OHMS, TR=2.5ns, TF=2.5ns SEE AC FIGS

SYMBOL	PARAMETER	CONDITIONS	NOTES	PIN-NAME	MIN	MAX	UNIT	SUB-GROUPS
tpLH(1)	Propagation Delay	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C	2, 4	CP to Qn	2.5	7.0	ns	9
			2, 4	CP to Qn	2.5	9.0	ns	10, 11
tpHL(1)	Propagation Delay	VCC= 5.0V @25C, VCC=4.5V & 5.5V @-55/125C	2, 4	CP to Qn	3.0	7.5	ns	9
			2, 4	CP to Qn	3.0	8.5	ns	10, 11
tpHL	Propagation Delay	VCC= 5.0V @25C, VCC=4.5V & 5.5V @-55/125C	2, 4	$\overline{MR}$ to Qn	4.0	10.5	ns	9
			2, 4	$\overline{MR}$ to Qn	4.0	12.5	ns	10, 11
ts(L)	Setup Time (Low)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C	5	A or B to CP	3.0		ns	9
			5	A or B to CP	4.0		ns	10, 11
ts(H)	Setup Time (High)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C	5	A or B to CP	4.5		ns	9
			5	A or B to CP	5.5		ns	10, 11
th(H/L)	Hold Time (High or Low)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C	5	A or B to CP	1.0		ns	9, 10, 11
tw(L)	Pulse Width (Low)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C, TR/TF=1.0ns	5	CP	7.0		ns	9, 10, 11
			5	CP			ns	
tw(H)	Pulse Width (High)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C, TR/TF=1.0ns	5	CP	4.0		ns	9, 10, 11
tw (L)	Pulse Width (Low)	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C, TR/TF=1.0ns	5	$\overline{MR}$	5.0		ns	9, 10, 11
tREC	Recovery Time	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C	5	$\overline{MR}$ to CP	5.5		ns	9
			5	$\overline{MR}$ to CP	6.5		ns	10, 11
fMAX	Maximum Count Frequency	VCC=5.0V @25C, VCC=4.5V & 5.5V @-55/125C, TR/TF=1.0ns	5		80		MHZ	9
			5		60		MHZ	10, 11

Note 1: Screen tested 100% on each device at +25C, +125C & -55C temperature, subgroups A1, 2, 3, 7 & 8.
Note 2: Screen tested 100% on each device at +25C temperature only, subgroup A9.
Note 3: Sample tested (Method 5005, Table 1) on each MFG. lot at +25C, +125C & -55C temperature, subgroups A1, 2, 3, 7 & 8.
Note 4: Sample tested (Method 5005, Table 1) on each MFG. lot at +25C subgroup A9, and periodically at +125C & -55C temperature, subgroups 10 & 11.

(Continued)

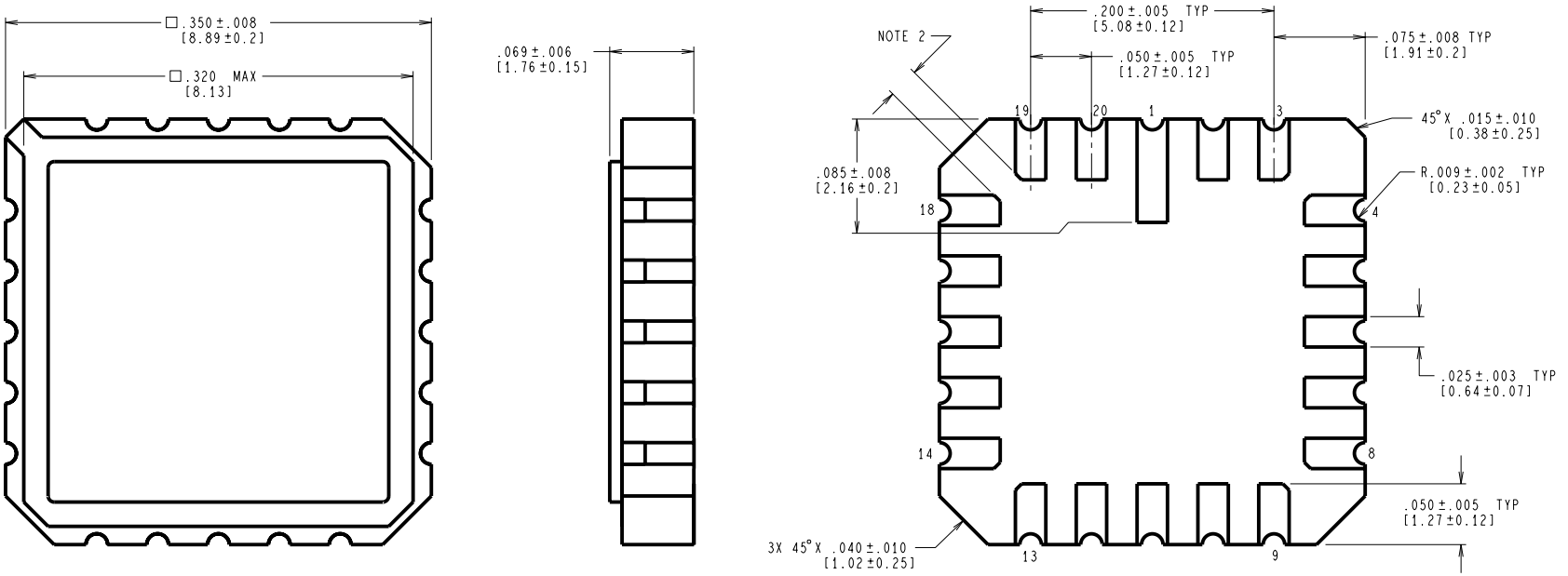
Note 5: Guaranteed but not tested. (DESIGN CHARACTERIZATION DATA)

Graphics and Diagrams

GRAPHICS#	DESCRIPTION
E20ARE	LCC (E), TYPE C, 20 TERMINAL(P/P DWG)
J14ARH	CERDIP (J), 14 LEAD (P/P DWG)
W14BRN	CERPACK (W), 14 LEAD (P/P DWG)

See attached graphics following this page.

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
E	REVISE AND REDRAW.	10005	02/10/94	DEG/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH TO BE ONE OF THE FOLLOWING:

   a. 50 MICROINCHES/12.7 MICROMETERS MINIMUM GOLD PLATING OVER 50-350 MICROINCHES/1.27-8.89 MICROMETERS NICKEL.

   b. SOLDER DIP.
   SOLDER THICKNESS PER LATEST REVISION OF MIL-STD-1835.

2. CORNER PADS MAY HAVE A 45°X.020IN/0.51mm MAXIMUM CHAMFER TO ACCOMPLISH THE .015IN/0.38mm DIMENSION.

4. REFERENCE JEDEC REGISTRATION MS-004, VARIATION CB, DATED 7/90.

CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

MIL/AERO
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN: Dwayne Grady	02/10/94
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	

PROJECTION
INCH [MM]

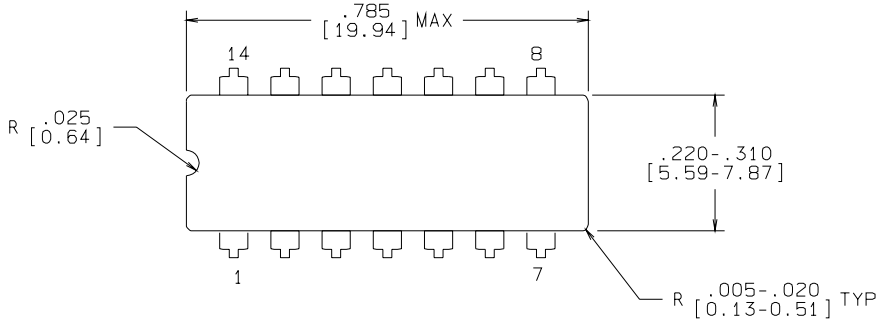
NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

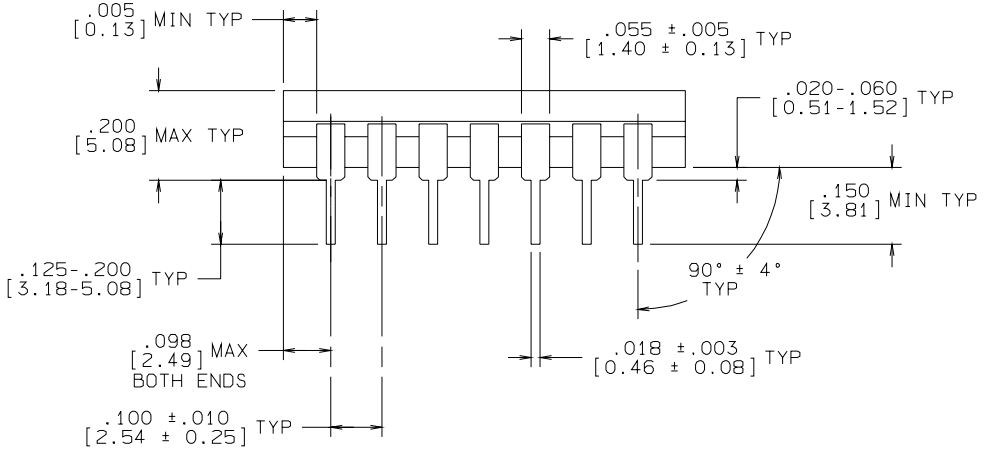
LEADLESS CHIP CARRIER, TYPE C, 20 TERMINAL

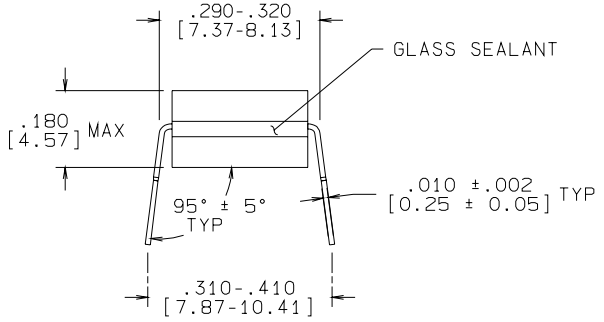
SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-E20A	E

DO NOT SCALE DRAWING | SHEET 1 of 1

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
H	REVISE PER CURRENT STD; REDRAW	10001	09/15/93	TL/







CONTROLLING DIMENSION: INCH

MIL/AERO CONFIGURATION CONTROL

MIL-M-38510 CONFIGURATION CONTROL

NOTES: UNLESS OTHERWISE SPECIFIED

1. LEAD FINISH TO BE 200 MICROINCHES / 5.08 MICROMETERS MINIMUM SOLDER MEASURED AT THE CREST OF THE MAJOR FLATS.
2. JEDEC REGISTRATION MO-036, VARIATION AB, DATED 04/1981.

APPROVALS	DATE
DRAWN T. LEQUANG	09/15/93
DFTG. CHK.	
ENGR. CHK.	
APPROVAL	

PROJECTION

INCH [MM]

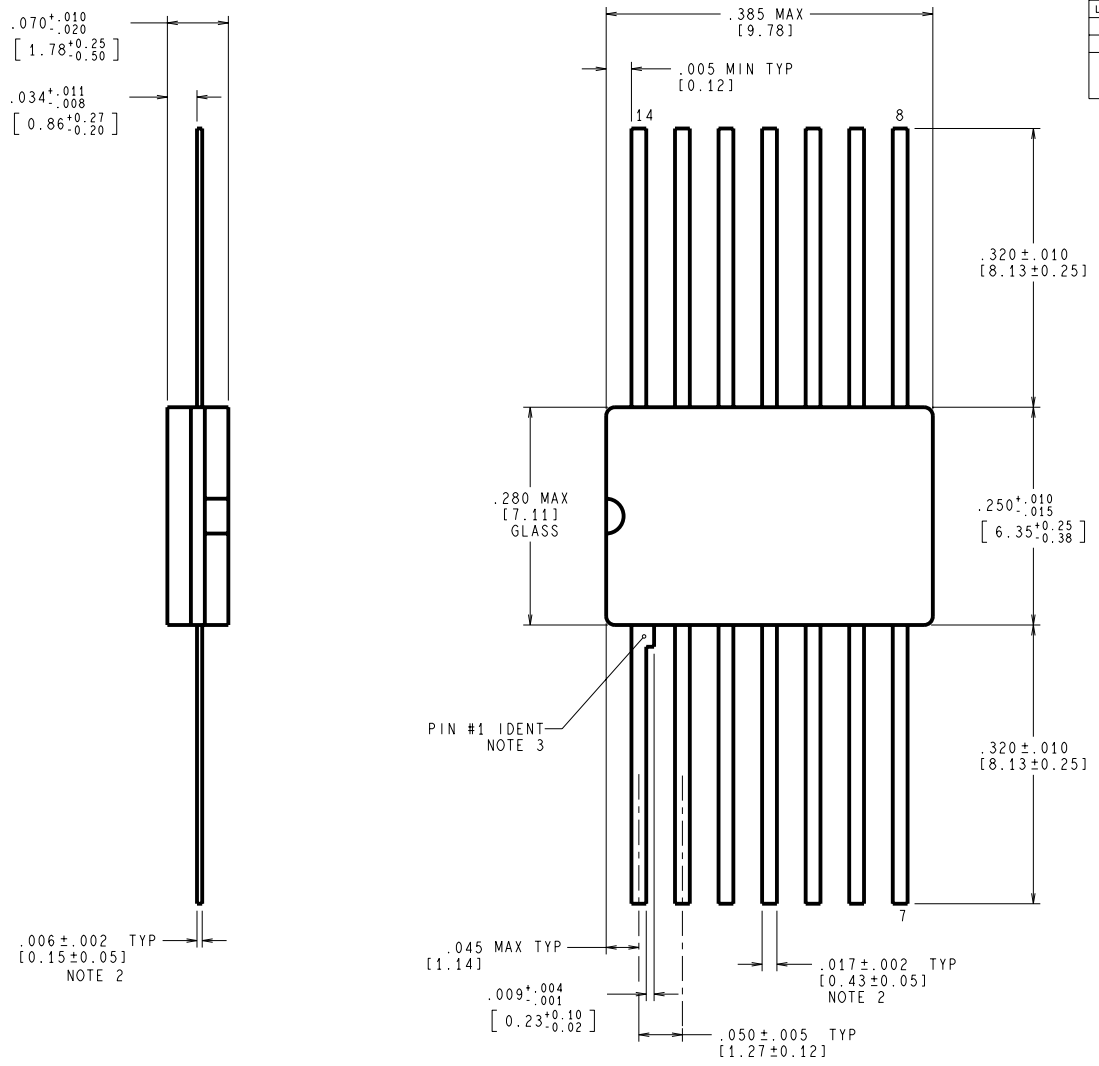
NATIONAL SEMICONDUCTOR CORPORATION
2900 Semiconductor Drive, Santa Clara, CA 95052-8090

CERDIP (J), 14 LEAD,

SCALE	SIZE	DRAWING NUMBER	REV
N/A	B	MKT-J14A	H

DO NOT SCALE DRAWING | SHEET 1 OF 1

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
L	REVISE AND REDRAW PER NEW STANDARD.	10513	07/26/94	DEG/AEP
M	.017±.002 WAS .017±.020.	10655	10/21/94	DEG/CD
N	L/F THKS .006±.002 WAS .005±.001; UPDATE NOTES 1 & 2; REMOVE NOTE 4; UPDATE MILAERO STAMP; DUAL DIM'S WERE INCHES ONLY.	11005	06/08/95	MS/



NOTES: UNLESS OTHERWISE SPECIFIED.

1. LEAD FINISH: SOLDER DIPPED WITH Sn60 OR Sn63 SOLDER CONFORMING TO MIL-I-38535 TO A MINIMUM THICKNESS OF 200 MICROINCHES/ 5.08 MICROMETERS. SOLDER MAY BE APPLIED OVER LEAD BASIS METAL OR Sn PLATE.
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES/ 0.08 MILLIMETERS AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
   a) A NOTCH OR OTHER MARK WITHIN THIS AREA
   b) A TAB ON LEAD 1, EITHER SIDE

CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

MIL-I-38535
CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN D.E.Grady	07/26/94
DFTG. CHK.	
ENGR. CHK.	

PROJECTION INCH [MM]

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

CERPACK, 14 LEAD

SCALE	SIZE	DRAWING NUMBER	REV
N/A	C	MKT-W14B	N

DO NOT SCALE DRAWING | SHEET 1 of 1

Revision History

Rev	ECN #	Rel Date	Originator	Changes
1B0	M0004026	06/21/02	Rose Malone	Update MDS: MN54F164A-X, Rev. 1A0 to MN54F164A-X, Rev. 1B0. Updated NS Part Numbers on Main Table, Added Mkt Dwg.'s to Graphics Section.